

O I P E
 CITATION
 FEB 17 2004
 PATENT & TRADEMARK OFFICE

Order Number (Customer)

TSMC-03-299

License Number

10/714,985

! Important!

'William Hong et al.

Expanding Dates

11/17/03

Group Art Unit

2813

~~SECRET~~ DOCUMENTS

FOREIGN PATENT DOCUMENTS

[illegible]

OTHER DOCUMENTS (Including Author, Title, Date, Portion, Pages, Etc.)

IN	-	Co-pending U.S. Patent TSMC-02-992, Serial # 10/723,236, filed on 11/26/03, same assignee, "An Advanced Process Control Approach for Cu Interconnect Wiring Sheet Resistance Control"
IN	-	Co-pending U.S. Patent TSMC-03-424, Serial # 10/627,795, filed on 07/25/03, same assignee, "Barrier-Slurry-Free Copper CMP Process"

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Chair

DATE CONSIDERED

1/3/105

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